



- Light cure in seconds
- High-strength bonds
- Room temperature light/activator cure
- Thick viscosity
- Low CTE
- Stable at room temperature
- One component - No mixing required

Multi-Cure® Thermal Management Adhesives

Rapid Mounting of Heat-Sensitive Components on Printed Circuit Boards

Dymax Multi-Cure® thermally-conductive adhesives provide an efficient method of thermal transfer between heat sinks and electronics. They cure in seconds upon exposure to UV/Visible light, providing cutting edge performance characteristics with maximum processing convenience. These adhesives may be used for mounting heat sinks and heat-sensitive electronic components to printed circuit boards or for use in any application where it is desirable to increase thermal conductivity between assembled parts. Thermal management adhesives eliminate the need for mechanical fasteners and clips.

Benefits

- Remains in place prior to part being mated
- Instant fixture for immediate movement to next process
- Long-term reliability
- No heat exposure required
- Minimal expansion during thermal rise
- No refrigeration necessary
- No mixing required

Products

Product	Description	Cure Methods and Cure Schedules	Specific Gravity, g/m	Viscosity, cP	Tensile Shear Strength, MPa [psi]	Thermal Range, °C [°F]	Thermal Conductivity, W/m•K	Coefficient of Thermal Expansion, in/in/°C	Dielectric Strength, V/mil*
9-20801	Acrylated urethane; off white	UV light: 10-30 sec.	2.0	110,000	14 [2,100]	-50 to 175 [-65 to 350]	0.9	45 x 10 ⁻⁶	1,600
		Activator: Fixture: 30-60 sec at RT* Full cure: 2 hours at RT							
		Heat: 120°C for 20-30 min 150°C for 10-15 min							
501-E-REV-A Activator	Amber; pre-application of 501-E provides fast fixtures and room temperature bonding for heat sinks								

*RT = room temperature

* Measured in a 2 mil thick layer. Dielectric strength varies with thickness of the adhesive



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